

DVD150T



100V^{RF} Power FET

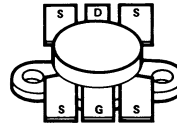
175 MHz 120 W 100 MHz 150 W
 80-120 V 10 dB 80-120 V 17 dB

Other Devices in Series:
 DVD030S

FEATURES

- Infinite VSWR
- No Thermal Runaway
- Broadband Capability
- Class A, B, C, D, E
- Low Noise Figure
- High Dynamic Range
- Simple Bias Circuitry
- Lower I²R Losses

Package Type T



.500 JO Flange

See page 5-62 for Package Dimensions

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Gate-Source Voltage	40V	Total Device Dissipation	240W
Drain-Source Voltage	220V	Thermal Resistance, Junction to Case . .	0.73°C/W
Drain-Gate Voltage	220V	Junction Temperature	200°C
Drain Current (DC)	4.8A	Storage Temperature	-65°C to +150°C

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Characteristics	Min	Typ	Max	Unit	Test Conditions
BV _{DSS}	Drain-Source Breakdown Voltage	220			V	V _{GS} = 0V, I _D = 30 mA
I _{DSS}	Drain-Source Leakage Current			6.0	mA	V _{GS} = 0V, V _{DS} = 100V
I _{GSS}	Gate-Source Leakage Current			100	nA	V _{GS} = 40V, V _{DS} = 0V
g _m ¹	D.C. Forward Transconductance	1.0			Mho	V _{DS} = 50V, I _D = 5A, ΔV _{GS} = 1.0V
I _{D(on)} ¹	On-State Drain Current	1.5			A	V _{DS} = 50V, V _{GS} = 5V
V _{GS(th)}	Gate Threshold Voltage	2.0		6.0	V	V _{GS} = V _{DS} , I _D = 1.0 Amp
C _{iss}	Common-Source Input Capacitance			400	pF	V _{GS} = 0V, V _{DS} = 30V, f = 1.0 MHz
C _{oss}	Common-Source Output Capacitance			100	pF	V _{GS} = 0V, V _{DS} = 30V, f = 1.0 MHz
C _{rss}	Reverse Transfer Capacitance			15	pF	V _{GS} = 0V, V _{DS} = 30V, f = 1.0 MHz
G _{ps}	Common-Source Power Gain	10	17		dB	V _{DD} = 100V, V _{GS} = 0V, P _o = 120W, f = 175 MHz V _{DD} = 100V, V _{GS} = 0V, P _o = 150W, f = 100 MHz
η	Drain Efficiency		65		%	V _{DD} = 100V, P _o = 120W, f = 175 MHz, V _{GS} = 0V
V _{SWR}	Load Mismatch Tolerance	30:1				V _{DD} = 100V, P _o = 120W, f = 175 MHz, I _{D(max)} = 2.4A

Note 1: Pulse Test — 80μs to 300μs, 1% duty cycle

TYPICAL PERFORMANCE CURVES

FIGURE 1 Transfer Characteristics

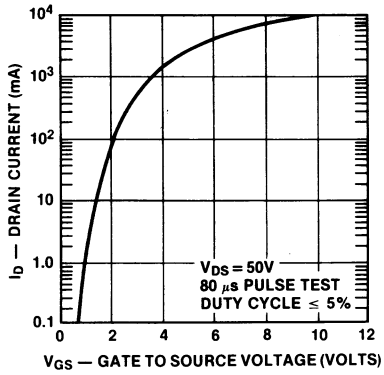


FIGURE 2 Output Characteristics

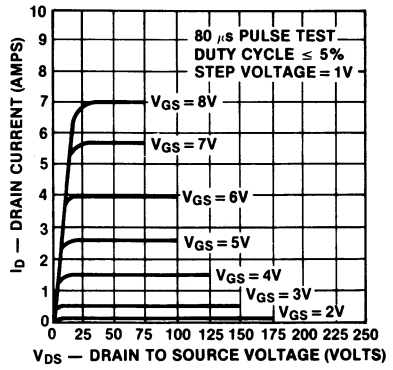


FIGURE 3 Transconductance vs. Drain Current

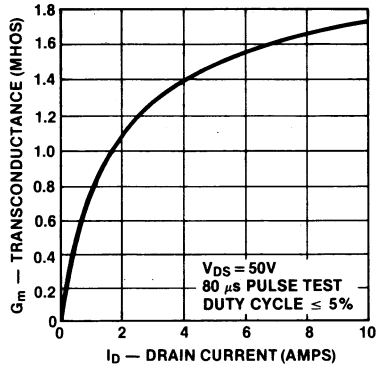


FIGURE 4 MTTF vs. Chip Temperature

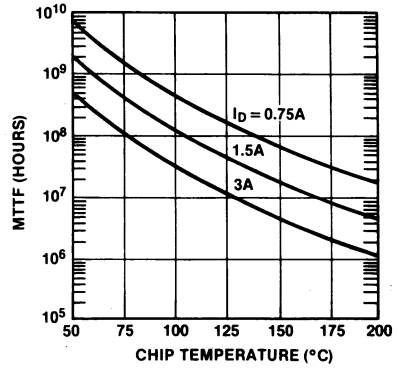


FIGURE 5 DC Safe Operating Region

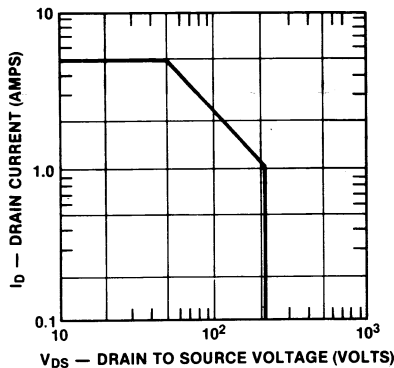


FIGURE 6 Series Equivalent Input Impedance vs. Frequency

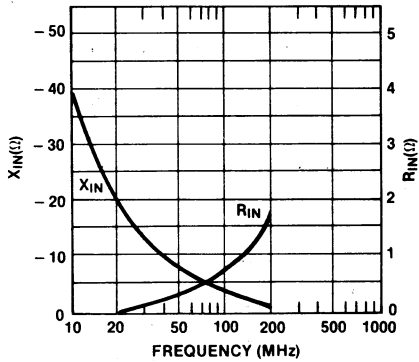
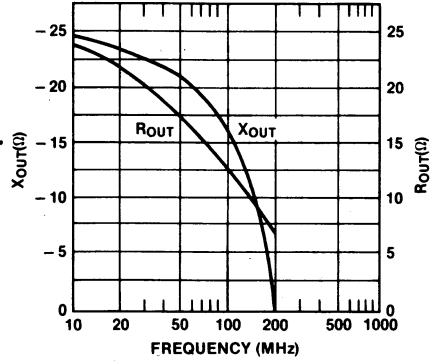
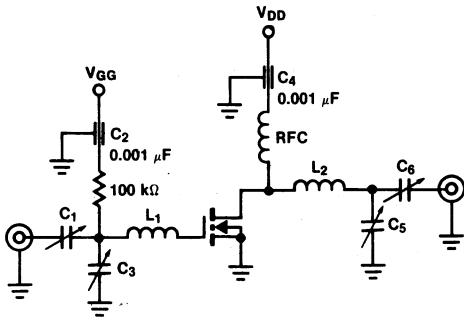


FIGURE 7 Series Equivalent Output Impedance vs. Frequency



RF TEST FIXTURES

FIGURE 8 175 MHz Test Fixture



PARTS LIST

- C1, C3, C5, C6, ARCO #462, 5 TO 80 pF TRIMMER CAPACITORS
- L1, L2, 1 1/2 TURNS #12 AWG AIR WOUND, 5/16" IN DIA.
- RFC, 10-TURNS #20 AWG ENAMEL ON 1/4" DIA., CLOSE WOUND

FIGURE 9 Typical Power Out vs. Power In

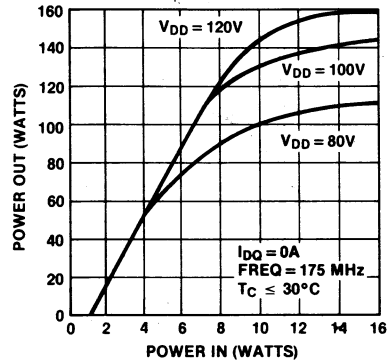
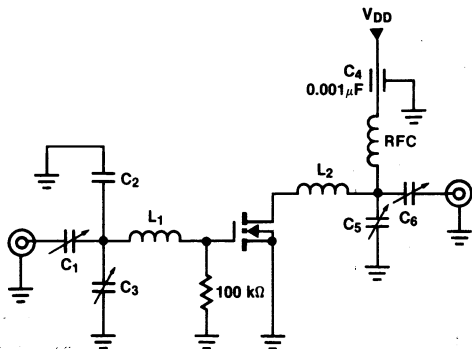
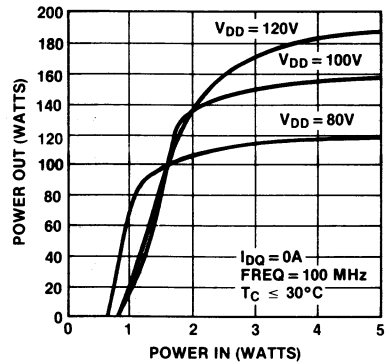


FIGURE 10 100 Volt VNR 100 MHz Test Fixture



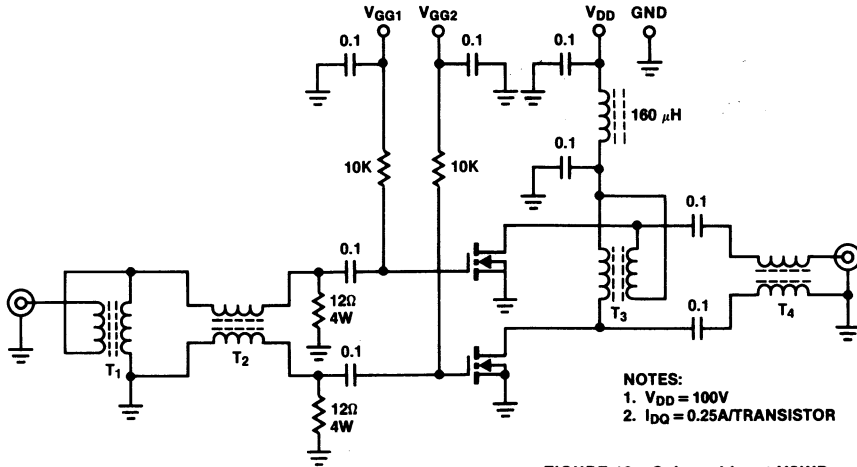
- C1, C5, C6 ARCO #462 5 TO 80 pF TRIMMER CAPACITOR
- C2, 30 pF SEMCO POWER CAPACITOR
- C3, ARCO #422 4 TO 40 pF TRIMMER CAPACITOR
- RFC, 13-TURNS #18 AWG CLOSE WOUND ON 0.3" DIA.
- L1, 3-TURNS #12 AWG ON 0.3" DIA.
- L2, 5-TURNS #12 AWG ON 0.3" DIA.

FIGURE 11 Power Out vs. Power In



APPLICATIONS

FIGURE 12 2-30 MHz Linear Amplifier



- NOTES:
 1. $V_{DD} = 100V$
 2. $I_{DQ} = 0.25A/TRANSISTOR$

PARTS LIST

- T₁ 4:1 TRANSFORMER
 4 TURNS OF TWO 50Ω COAX IN PARALLEL THROUGH SIX INDIANA GENERAL FERRITE CORES PN F627-8-Q1
- T₂ 12.5Ω BALUN
 2 TURNS OF FOUR 50Ω COAX IN PARALLEL THROUGH SIX INDIANA GENERAL FERRITE CORES PN F627-8-Q1
- T₃ 4:1 TRANSFORMER
 4 TURNS OF TWO 50Ω COAX IN PARALLEL THROUGH SIX INDIANA GENERAL FERRITE CORES PN F627-8-Q1
- T₄ 50Ω BALUN
 6 TURNS OF 50Ω COAX THROUGH SIX INDIANA GENERAL FERRITE CORES PN F627-8-Q1

FIGURE 13 Gain and Input VSWR vs. Frequency

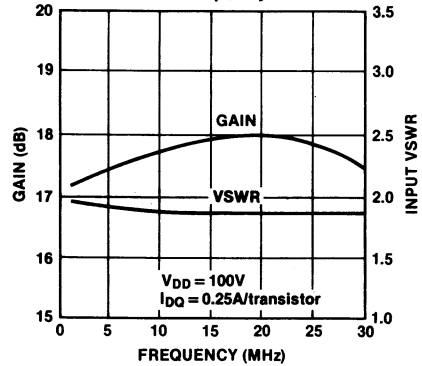


FIGURE 14 Intermodulation Ratio vs. Output Power (30 MHz)

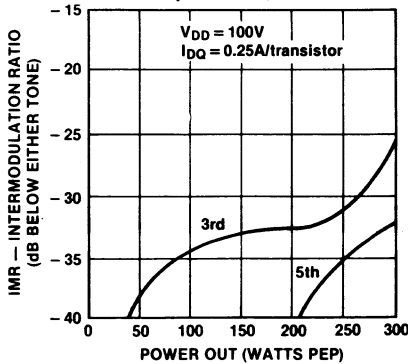
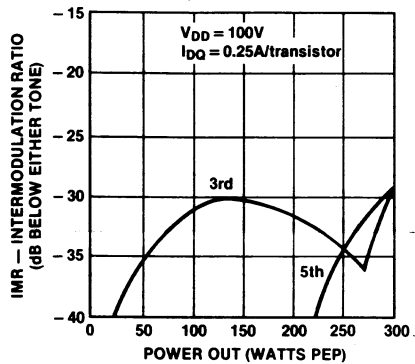


FIGURE 15 Intermodulation Ratio vs. Output Power (2 MHz)



CAUTION: Beryllium Oxide — The top cap of this device is alumina which is harmless. However, the ceramic portion between the leads and the metal flange is Beryllium Oxide, the dust of which is toxic. Care must therefore be taken during handling and mounting the device to prevent any damage to this area.

Steps must be taken to ensure that all those who may handle, use, or dispose of this device are aware of its nature and of these necessary safety precautions. In particular the transistor should never be thrown out with general industrial or domestic waste.